

#### FEATURES

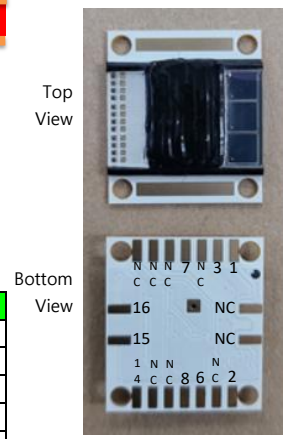
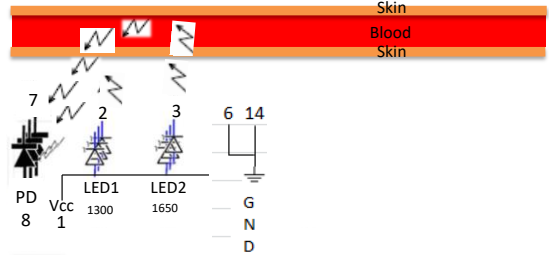
Integrated Dual Emitters and Triple Photo Detectors Array  
 IR1(1300nm), IR2(1650nm) LED Lightings  
 Chip on Board Package

**Package Dimension (mm)**  
 w x h x t = 19 x 16.6 x 1.5  
 PAD = 1.0 x 2.45

#### APPLICATIONS

Reflective Sensing  
 Wearable Optical Device  
 Body Tissue Monitoring

#### SCHEMATIC



#### ABSOLUTE MAX. RATINGS (Ta=25°C unless otherwise noted)

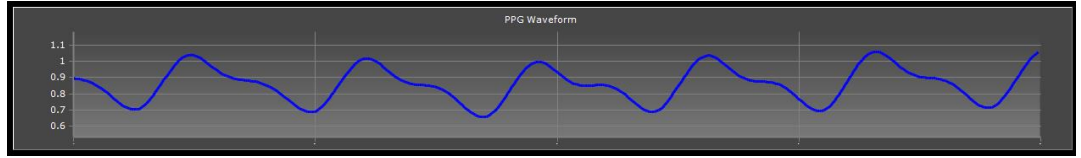
SYMBOL	PARAMETER	MAX. RATED VALUE	UNITS
PD	Power Dissipation	120	mW
IF	Continuous Forward Current	50	mA
IFP	Peak Forward Current	100	mA
VR	Reverse Voltage	5	V
T stg	Storage Temp	-20 ~ +85	°C
T opr	Operating Temp	-20 ~ +80	°C
T sd	Soldering Temperature*1	240	°C

\*Soldering time : t < 3s, \*\*Moisture Sensitivity Level 3  
 \*\*\*Prebake 150°C 2HRs if Reflow Soldering

#### CHARACTERISTICS (Ta=25°C unless otherwise noted)

SYMBOL	CHARACTERISCTIC	COMPONENTS	TEST CONDITION	MIN	TYP	MAX	UNITS	
VF	Forward Voltage	LED2	IF=20mA		0.83		V	
		LED1			0.95			
IR	Reverse Breakdown Current	PD	IF=10mA	0.5		1.3	uA	
		LED1,2	VR=5V			10		
P O	Output Power	LED2	IF=20mA		2.8		mW	
		LED1			5.8			
λ PEAK	Peak Wavelength	LED2	IF=20mA	1620	1650	1680	nm	
		LED1		1270	1300	1330		
		PD			1550			
Δλ	Half Wave Width	LED2	IF=20mA		30		nm	
		LED1			30			
V BR	Reverse Breakdown Voltage	PD	IR=100uA	30			V	
I D	Reverse Dark Current		VR=5V			5	nA	
S	Spectral Response Range				900	1550	1700	nm
CJ	Junction Capacitance		VR=5V, f=1MHz		170			pF

#### PPG(Photo Plethysmogram) Characteristic



#### Footprint Top View

